


# MATERIAL DECLARATION SHEET



Material Number	PTVS10-076C-TH			
Product Line	Semiconductor Products			
Compliance Date	November 30 <sup>th</sup> 2013			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.597900	Bisphenol Epoxy Resin	1675-54-3	40.00	5.99	14.98
				Epoxy Resin	25085-99-8	20.00	3.00	
				Crystalline Silica	14464-46-1	23.00	3.45	
				Brominated Epoxy Resin	40039-93-8	12.00	1.80	
				Iron Oxide	51274-00-1	2.00	0.30	
				Titanium Oxide	13463-67-7	3.00	0.45	
2	Electrodes	Copper	2.374743	Copper	7440-50-8	99.10	58.98	59.51
				Silver	7440-22-4	0.40	0.24	
				Other	-	0.50	0.30	
3	Terminations	Copper	0.503168	Copper	7440-50-8	99.50	12.55	12.61
				Other	-	0.50	0.06	
4	Termination Finish	Silver	0.001952	Silver	7440-22-4	100.00	0.05	0.05
5	Chip	Silicon Die	0.220728	Silicon	7440-21-3	85.73	4.74	5.53
				Aluminium	7429-90-5	4.99	0.28	
				Nickel	7440-02-0	8.85	0.49	
				Gold	7440-57-5	0.43	0.02	
6	Die Attach	Solder	0.155131	Lead	7439-92-1	92.50	3.60	3.89
				Tin	7440-31-5	5.00	0.19	
				Silver	7440-22-4	2.50	0.10	
7	Die Coating	Silicone	0.136805	Polysiloxane	63148-62-9	22.11	0.76	3.43
				Chromium Sesquioxide	1308-38-9	5.67	0.19	
				Fumed Silica	112945-52-5	11.11	0.38	
				Filler	Trade Secret	61.11	2.10	
		Total Weight	3.990426					